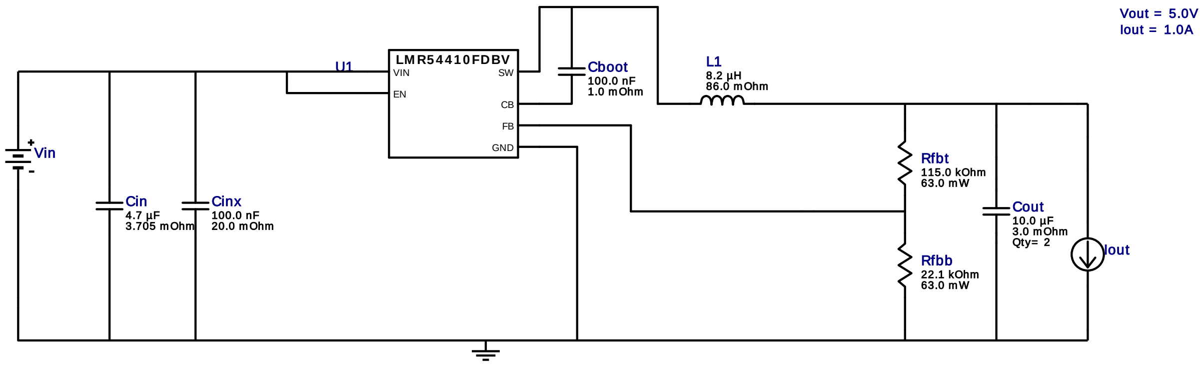
VinMin = 11.0V
VinMax = 16.0V
Vout = 5.0V
Iout = 1.0A

Device = LMR54410FDBVR
Topology = Buck
Created = 2023-12-08 23:25:29.060
BOM Cost = $1.70
BOM Count = 9
Total Pd = 0.55W

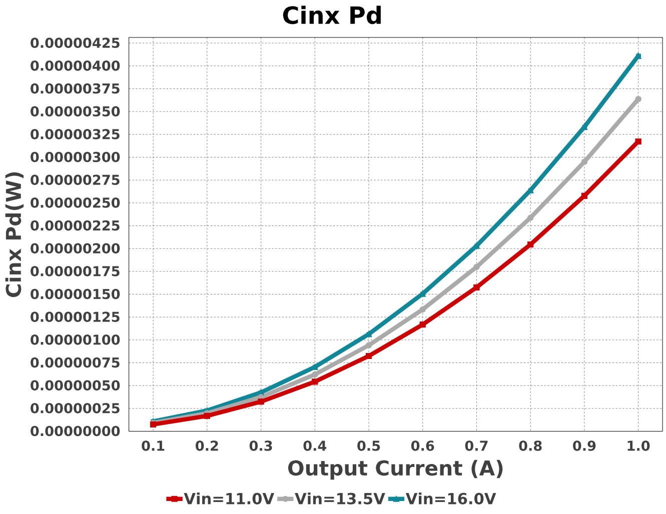
WEBENCH ® Design Report

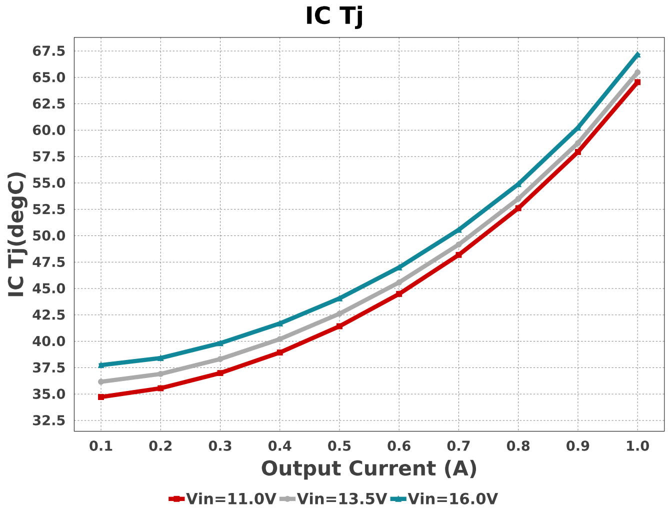
Design : 11 LMR54410FDBVR
LMR54410FDBVR 11V-16V to 5.00V @ 1A

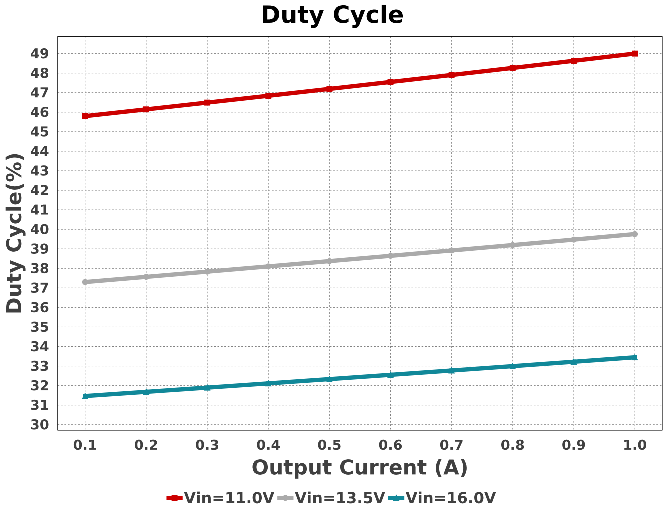


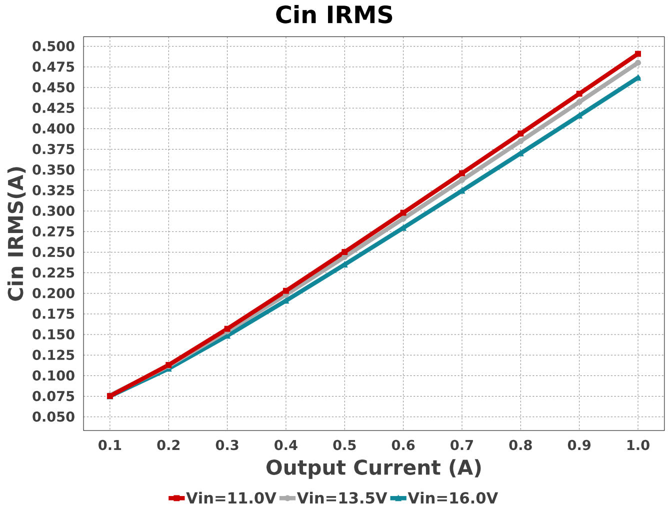
Electrical BOM

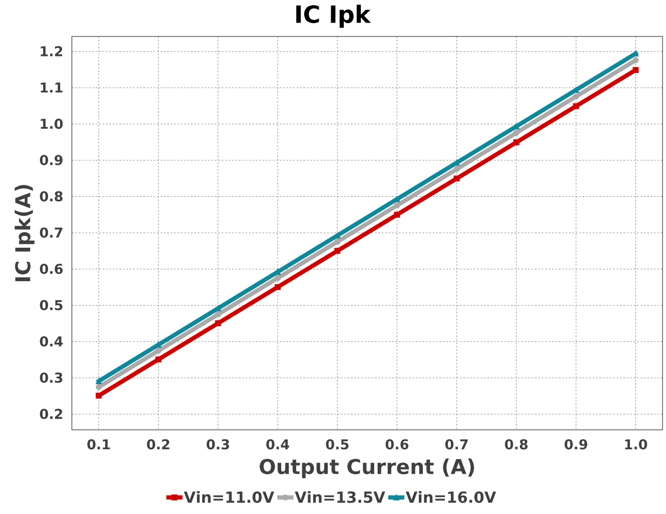
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cboot	MuRata	GRM155R71C104KA88D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	$0.01	0402 3 mm^2
Cin	MuRata	GRM31CR71E475KA88L Series= X7R	Cap= 4.7 uF ESR= 3.705 mOhm VDC= 25.0 V IRMS= 2.8649 A	1	$0.09	1206_190 11 mm^2
Cinx	MuRata	GRM188R71H104KA93D Series= X7R	Cap= 100.0 nF ESR= 20.0 mOhm VDC= 50.0 V IRMS= 3.8 A	1	$0.02	0603 5 mm^2
Cout	Kemet	C0805C106K8PACTU Series= X5R	Cap= 10.0 uF ESR= 3.0 mOhm VDC= 10.0 V IRMS= 11.43 A	2	$0.03	0805 7 mm^2
L1	Wurth Elektronik	74438357082	L= 8.2 µH 86.0 mOhm	1	$1.22	WE-MAPI_4030 26 mm^2
Rfbb	Vishay-Dale	CRCW040222K1FKED Series= CRCW..e3	Res= 22.1 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm^2
Rfbt	Vishay-Dale	CRCW0402115KFKED Series= CRCW..e3	Res= 115.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm^2
U1	Texas Instruments	LMR54410FDBVR	Switcher	1	$0.28	DBV0006A 15 mm^2

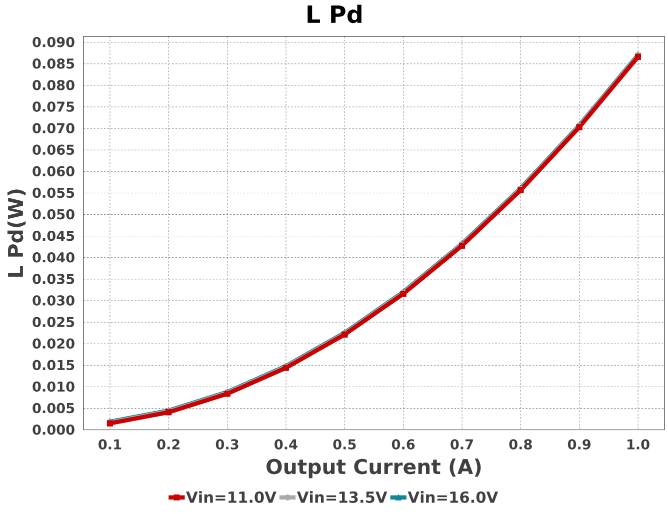

Cinx Pd
Cinx Pd(W)
0.00000425
0.00000400
0.00000375
0.00000350
0.00000325
0.00000300
0.00000275
0.00000250
0.00000225
0.00000200
0.00000175
0.00000150
0.00000125
0.00000100
0.00000075
0.00000050
0.00000025
0.00000000
0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9 1.0
Output Current (A)
Vin=11.0V Vin=13.5V Vin=16.0V

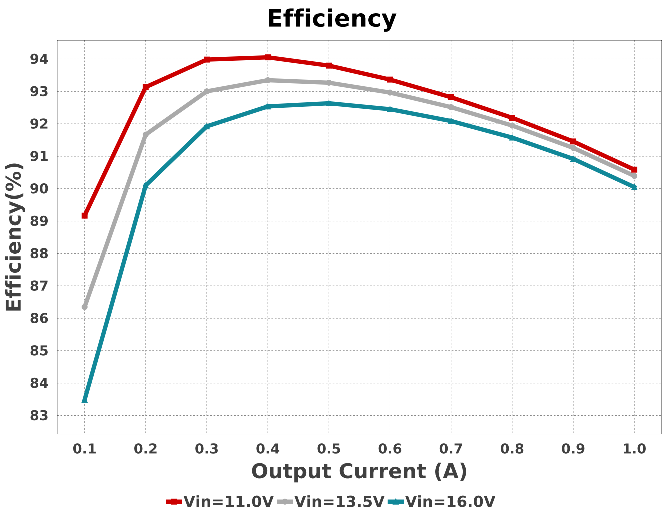

IC Tj
IC Tj(degC)
67.5
65.0
62.5
60.0
57.5
55.0
52.5
50.0
47.5
45.0
42.5
40.0
37.5
35.0
32.5
0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9 1.0
Output Current (A)
Vin=11.0V Vin=13.5V Vin=16.0V

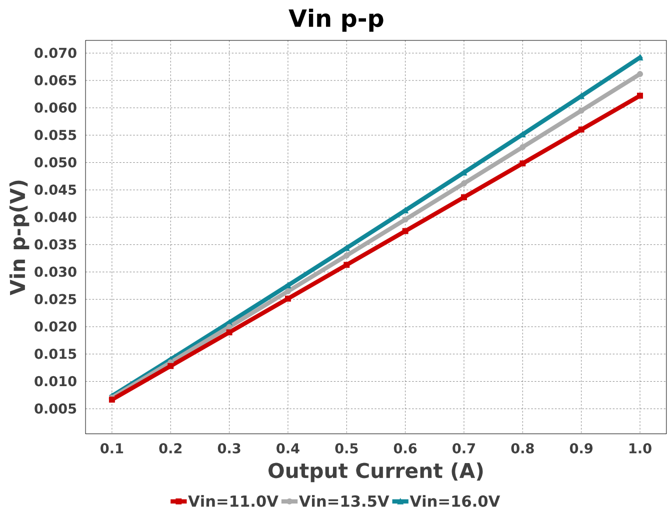

Duty Cycle
Duty Cycle(%)
49 48 47 46 45 44 43 42 41 40 39 38 37 36 35 34 33 32 31 30
0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9 1.0
Output Current (A)
Vin=11.0V Vin=13.5V Vin=16.0V

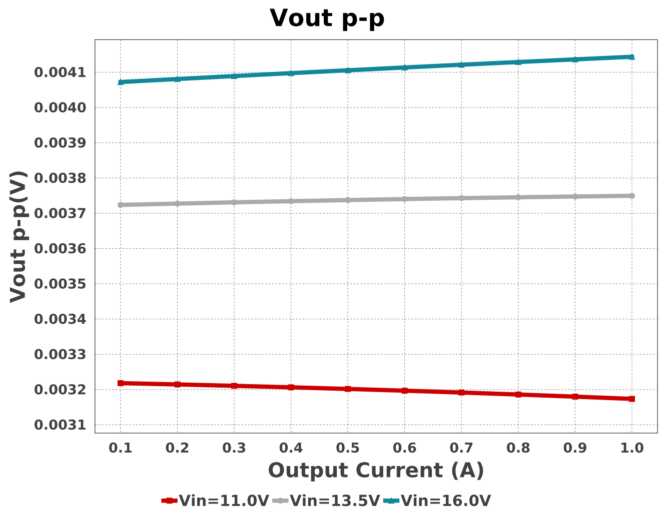

Cin IRMS
Cin IRMS(A)
0.500 0.475 0.450 0.425 0.400 0.375 0.350 0.325 0.300 0.275 0.250 0.225 0.200 0.175 0.150 0.125 0.100 0.075 0.050
0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9 1.0
Output Current (A)
Vin=11.0V Vin=13.5V Vin=16.0V

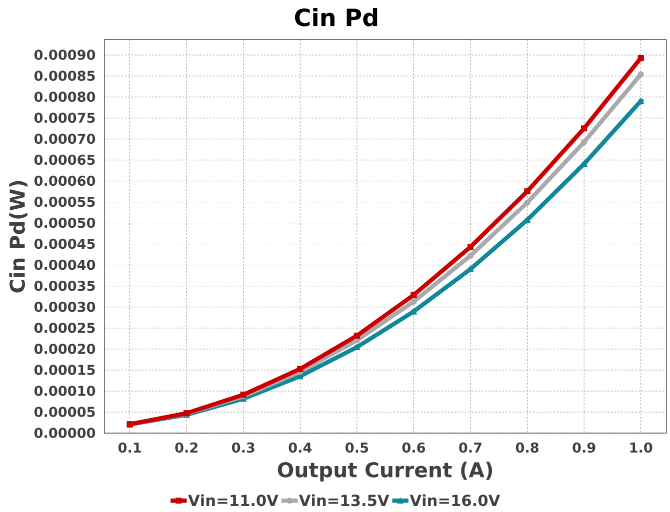

IC Ipk
IC Ipk(A)
1.2 1.1 1.0 0.9 0.8 0.7 0.6 0.5 0.4 0.3 0.2
0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9 1.0
Output Current (A)
Vin=11.0V Vin=13.5V Vin=16.0V

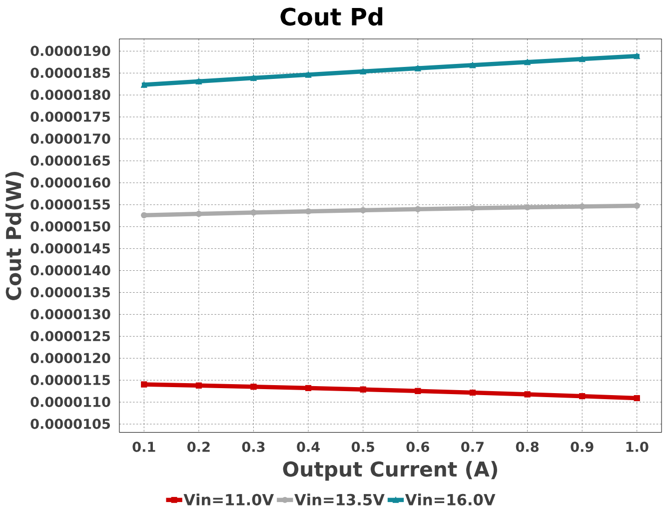

L Pd
L Pd(W)
0.090 0.085 0.080 0.075 0.070 0.065 0.060 0.055 0.050 0.045 0.040 0.035 0.030 0.025 0.020 0.015 0.010 0.005 0.000
0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9 1.0
Output Current (A)
Vin=11.0V Vin=13.5V Vin=16.0V

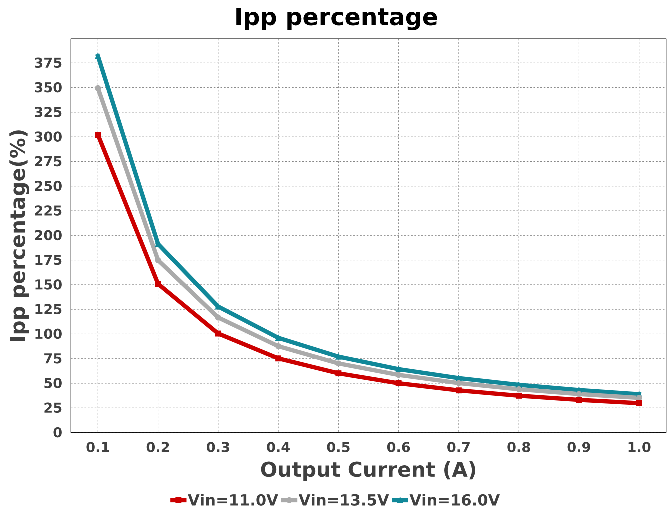

Efficiency
Efficiency(%)
Output Current (A)
Vin=11.0V
Vin=13.5V
Vin=16.0V

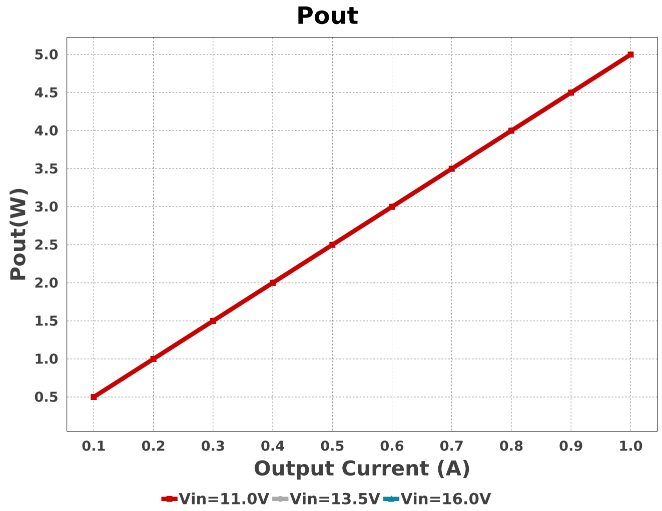

Vin p-p
Vin p-p(V)
Output Current (A)
Vin=11.0V
Vin=13.5V
Vin=16.0V

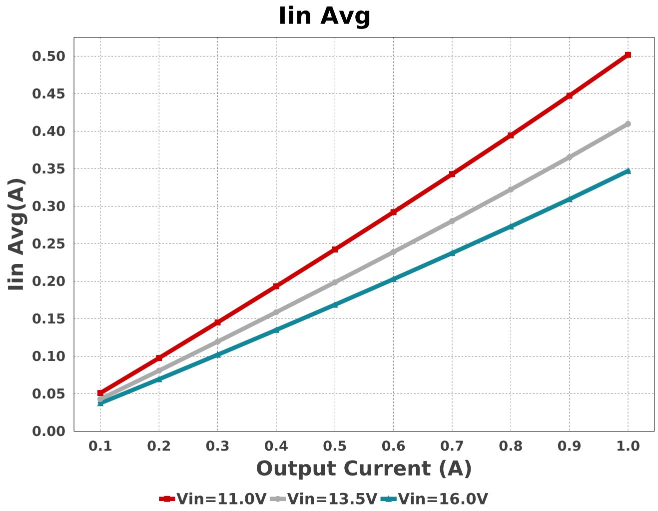

Vout p-p
Vout p-p(V)
Output Current (A)
Vin=11.0V
Vin=13.5V
Vin=16.0V

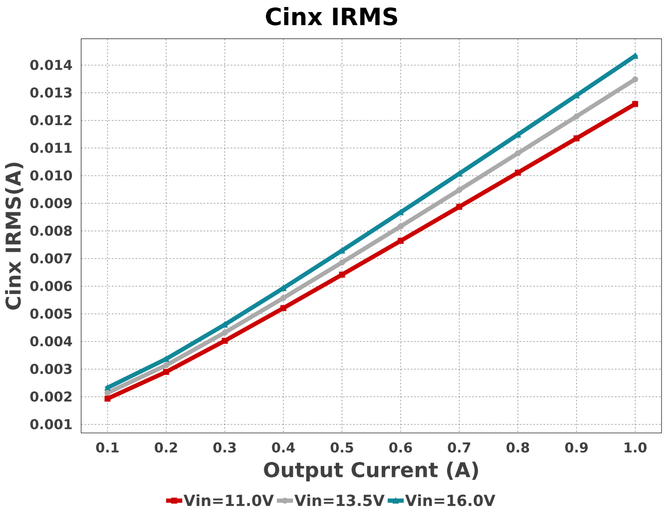

Cin Pd
Cin Pd(W)
Output Current (A)
Vin=11.0V
Vin=13.5V
Vin=16.0V

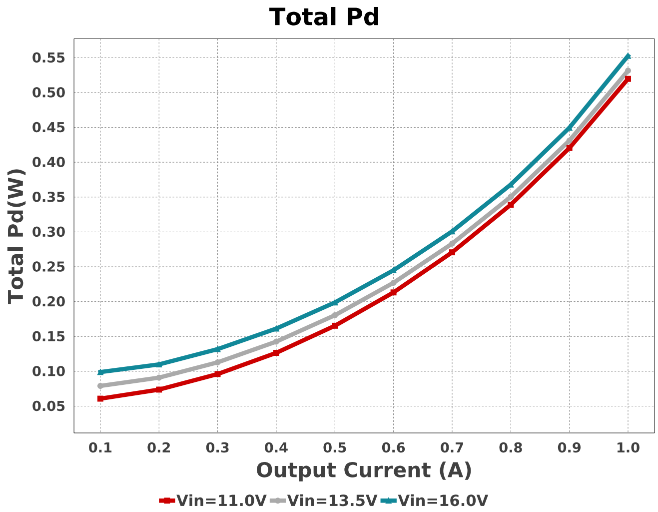

Cout Pd
Cout Pd(W)
Output Current (A)
Vin=11.0V
Vin=13.5V
Vin=16.0V

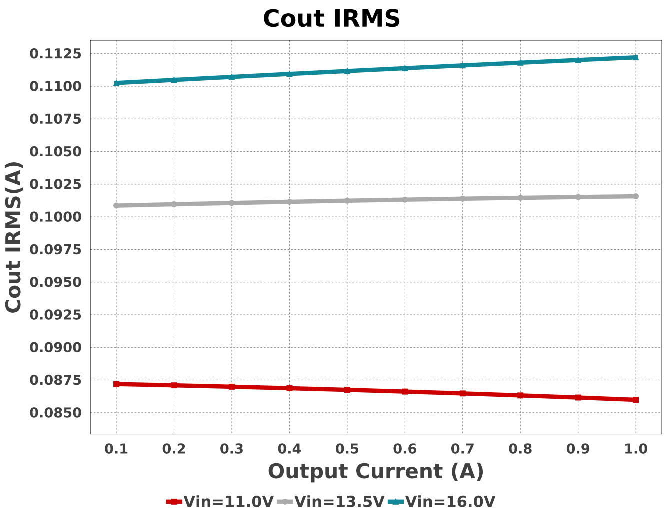

Ipp percentage
Ipp percentage(%)
Output Current (A)
Vin=11.0V
Vin=13.5V
Vin=16.0V

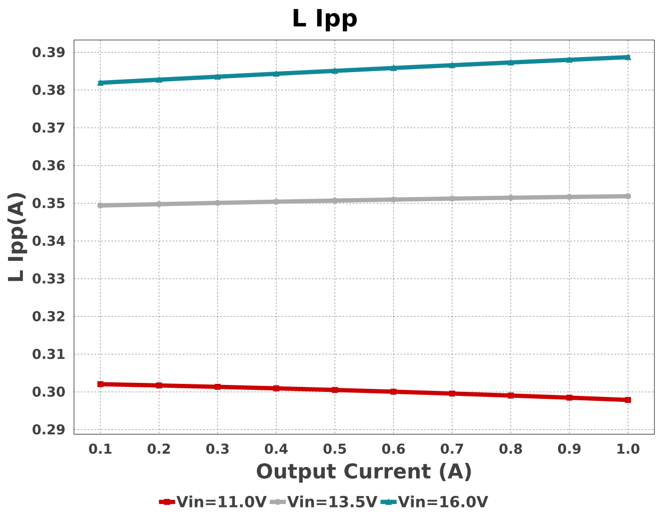

Pout
Pout(W)
Output Current (A)
Vin=11.0V Vin=13.5V Vin=16.0V

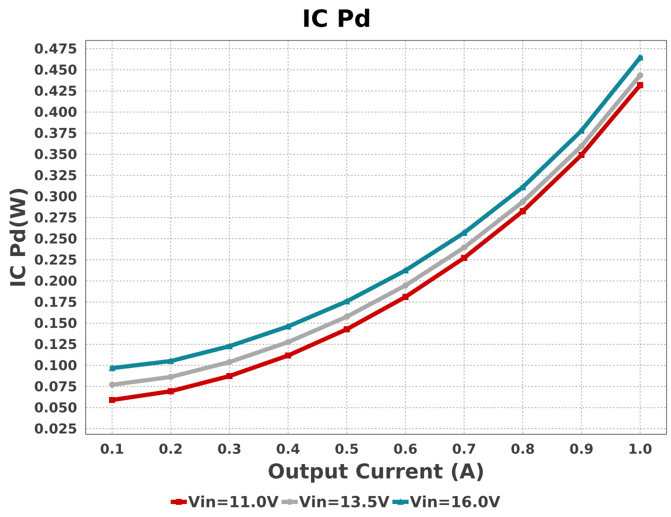

Iin Avg
Iin Avg(A)
Output Current (A)
Vin=11.0V Vin=13.5V Vin=16.0V

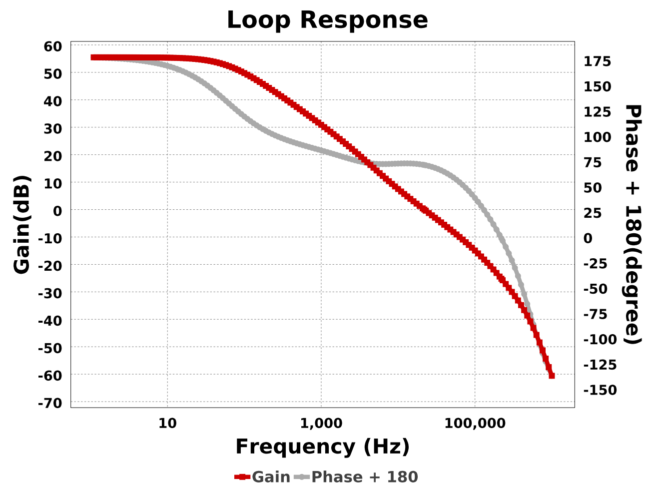

Cinx IRMS
Cinx IRMS(A)
Output Current (A)
Vin=11.0V Vin=13.5V Vin=16.0V


Total Pd
Total Pd(W)
Output Current (A)
Vin=11.0V Vin=13.5V Vin=16.0V


Cout IRMS
Cout IRMS(A)
Output Current (A)
Vin=11.0V Vin=13.5V Vin=16.0V


L Ipp
L Ipp(A)
Output Current (A)
Vin=11.0V Vin=13.5V Vin=16.0V





Operating Values

#	Name	Value	Category	Description
1.	BOM Count	9		Total Design BOM count
2.	Total BOM	$1.7		Total BOM Cost
3.	Cin IRMS	461.914 mA	Capacitor	Input capacitor RMS ripple current
4.	Cin Pd	790.52 µW	Capacitor	Input capacitor power dissipation
5.	Cinx IRMS	14.335 mA	Capacitor	Bulk capacitor RMS ripple current
6.	Cinx Pd	4.11 µW	Capacitor	Bulk capacitor power dissipation
7.	Cout IRMS	112.214 mA	Capacitor	Output capacitor RMS ripple current
8.	Cout Pd	18.888 µW	Capacitor	Output capacitor power dissipation
9.	IC Ipk	1.194 A	IC	Peak switch current in IC
10.	IC Pd	464.54 mW	IC	IC power dissipation
11.	IC Tj	67.163 degC	IC	IC junction temperature
12.	IC Tolerance	20.0 mV	IC	IC Feedback Tolerance
13.	ICThetaJA Effective	80.0 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance
14.	Iin Avg	347.04 mA	IC	Average input current
15.	Ipp percentage	38.872 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
16.	L Ipp	388.72 mA	Inductor	Peak-to-peak inductor ripple current
17.	L Pd	87.083 mW	Inductor	Inductor power dissipation
18.	Cin Pd	790.52 µW	Power	Input capacitor power dissipation
19.	Cinx Pd	4.11 µW	Power	Bulk capacitor power dissipation
20.	Cout Pd	18.888 µW	Power	Output capacitor power dissipation
21.	IC Pd	464.54 mW	Power	IC power dissipation
22.	L Pd	87.083 mW	Power	Inductor power dissipation
23.	Total Pd	552.599 mW	Power	Total Power Dissipation
24.	Cross Freq	21.934 kHz	System Information	Bode plot crossover frequency
25.	Duty Cycle	33.448 %	System Information	Duty cycle
26.	Efficiency	90.048 %	System Information	Steady state efficiency
27.	FootPrint	79.0 mm^2	System Information	Total Foot Print Area of BOM components
28.	Frequency	1.1 MHz	System Information	Switching frequency
29.	Gain Marg	-25.211 dB	System Information	Bode Plot Gain Margin
30.	Iout	1.0 A	System Information	Iout operating point
31.	Low Freq Gain	55.477 dB	System Information	Gain at 1Hz
32.	Mode	CCM	System Information	Conduction Mode
33.	Phase Marg	72.541 deg	System Information	Bode Plot Phase Margin
34.	Pout	5.0 W	System Information	Total output power
35.	Vin	16.0 V	System Information	Vin operating point
36.	Vin p-p	69.194 mV	System Information	Peak-to-peak input voltage
37.	Vout	5.0 V	System Information	Operational Output Voltage

#	Name	Value	Category	Description
38.	Vout Actual	4.963 V	System Information	Vout Actual calculated based on selected voltage divider resistors
39.	Vout Tolerance	4.237 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
40.	Vout p-p	4.144 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	1.0	Maximum Output Current
VinMax	16.0	Maximum input voltage
VinMin	11.0	Minimum input voltage
Vout	5.0	Output Voltage
base_pn	LMR54410F	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

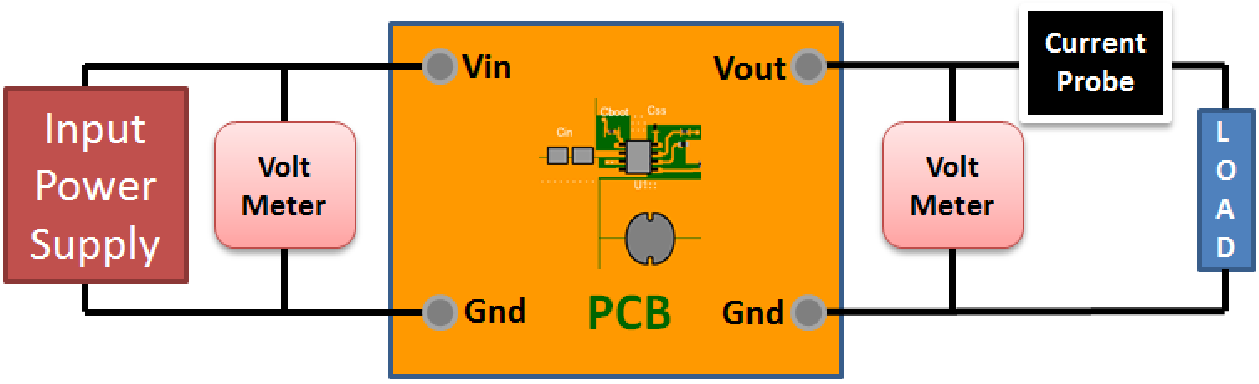
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 11.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum Iout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

1. Master key : 330B248541F6394ED110965082F3CA95[v1]

2. **LMR54410F** Product Folder : http://www.ti.com/product/LMR54410 : contains the data sheet and other resources.

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